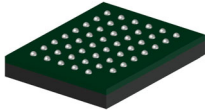


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS



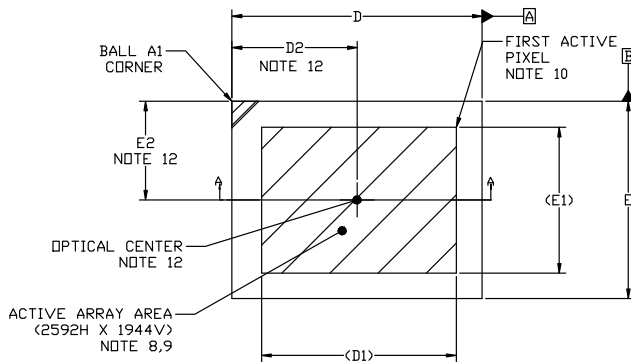
**ODCSP47 4.67x3.68x0.63, 0.50P**  
**CASE 570DD**  
**ISSUE O**

DATE 04 JAN 2024

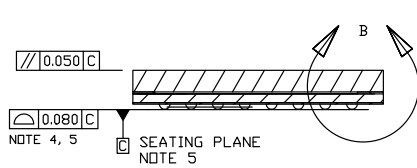
**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.040 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS  $\pm 0.1^\circ$ .
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.034, -0.005).

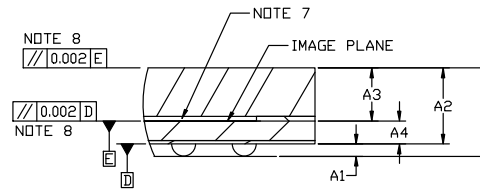
MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	0.762
A1	0.081	0.101	0.121
A2	0.606	0.631	0.656
A3	0.426	0.440	0.454
A4	0.180	0.191	0.202
b	0.184	0.204	0.224
D	4.645	4.670	4.695
D1	3.629 (REF)		
D2	2.344	2.369	2.394
E	3.657	3.682	3.707
E1	2.722 (REF)		
E2	1.821	1.846	1.871
e	0.500 BSC		



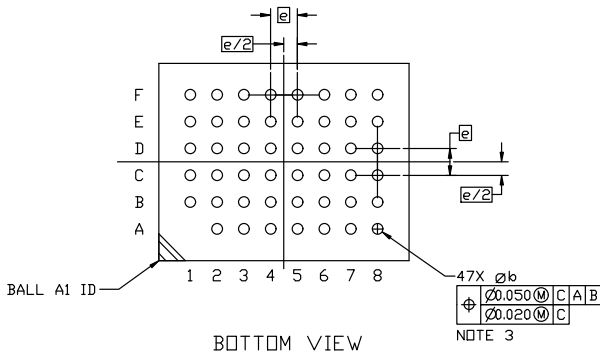
TOP VIEW



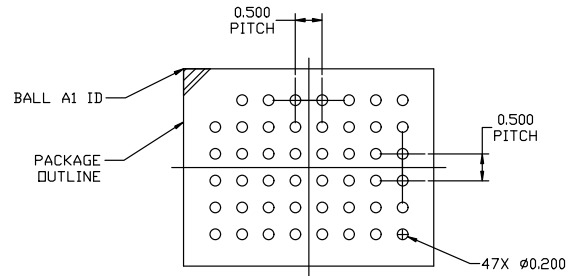
SECTION A-A



DETAIL B



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT

FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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